

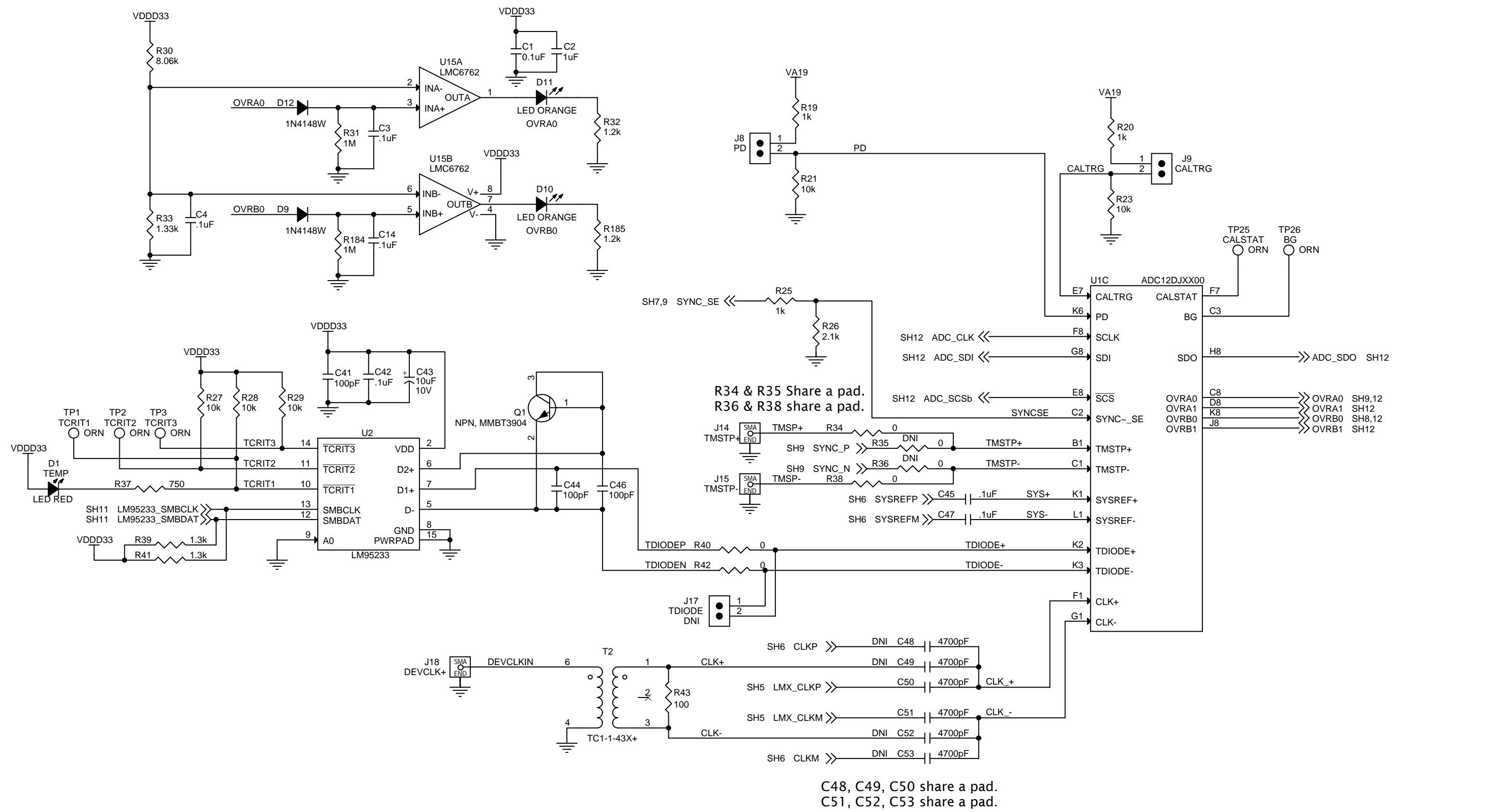
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DA1-	D12	DA1-	C8	.1uF	DA1_M	SH8
DA2+	A10	DA2+	C9	.1uF	DA2_P	SH8
DA2-	A11	DA2-	C10	.1uF	DA2_M	SH8
DA3+	A8	DA3+	C11	.1uF	DA3_P	SH8
DA3-	A9	DA3-	C12	.1uF	DA3_M	SH8
DA4+	E11	DA4+	C13	.1uF	DA4_P	SH8
DA4-	F11	DA4-	C15	.1uF	DA4_M	SH8
DA5+	C11	DA5+	C16	.1uF	DA5_P	SH8
DA5-	D11	DA5-	C18	.1uF	DA5_M	SH8
DA6+	B10	DA6+	C19	.1uF	DA6_P	SH10
DA6-	B11	DA6-	C21	.1uF	DA6_M	SH10
DA7+	B8	DA7+	C22	.1uF	DA7_P	SH10
DA7-	B9	DA7-	C23	.1uF	DA7_M	SH10
DB0+	H12	DB0+	C25	.1uF	DB0_P	SH8
DB0-	G12	DB0-	C26	.1uF	DB0_M	SH8
DB1+	K12	DB1+	C27	.1uF	DB1_P	SH8
DB1-	J12	DB1-	C28	.1uF	DB1_M	SH8
DB2+	M10	DB2+	C29	.1uF	DB2_P	SH8
DB2-	M11	DB2-	C30	.1uF	DB2_M	SH8
DB3+	M8	DB3+	C31	.1uF	DB3_P	SH8
DB3-	M9	DB3-	C32	.1uF	DB3_M	SH8
DB4+	H11	DB4+	C33	.1uF	DB4_P	SH10
DB4-	G11	DB4-	C34	.1uF	DB4_M	SH10
DB5+	K11	DB5+	C35	.1uF	DB5_P	SH10
DB5-	J11	DB5-	C36	.1uF	DB5_M	SH10
DB6+	L10	DB6+	C37	.1uF	DB6_P	SH10
DB6-	L11	DB6-	C38	.1uF	DB6_M	SH10
DB7+	L8	DB7+	C39	.1uF	DB7_P	SH10
DB7-	L9	DB7-	C40	.1uF	DB7_M	SH10

TEXAS INSTRUMENTS

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ANALOG IN

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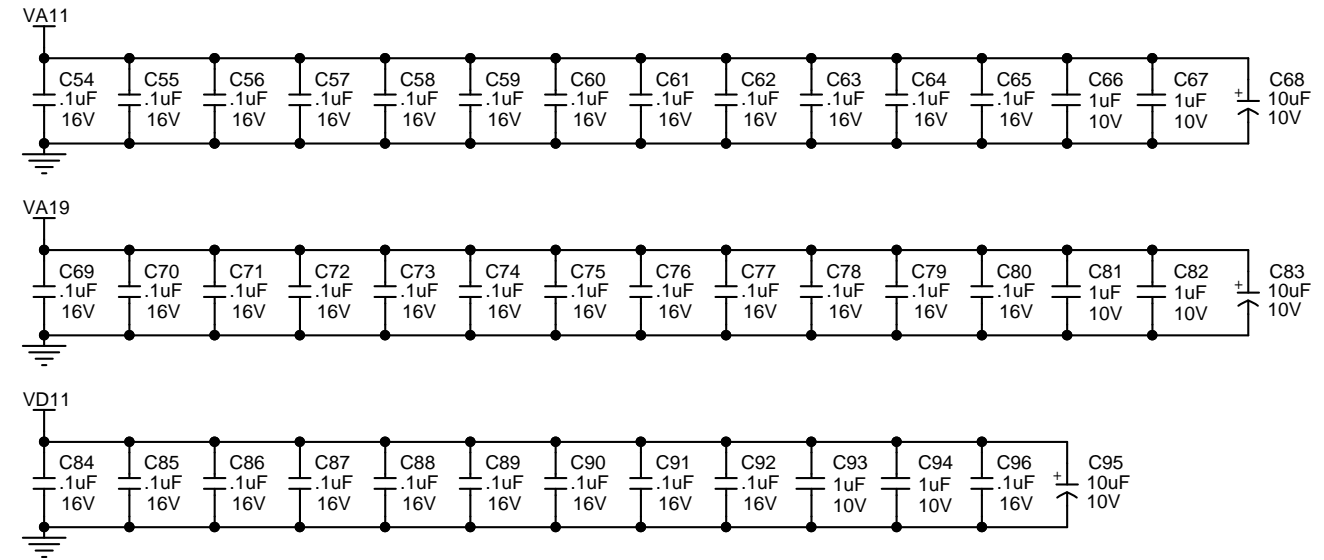
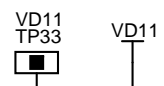
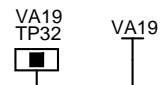
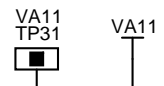
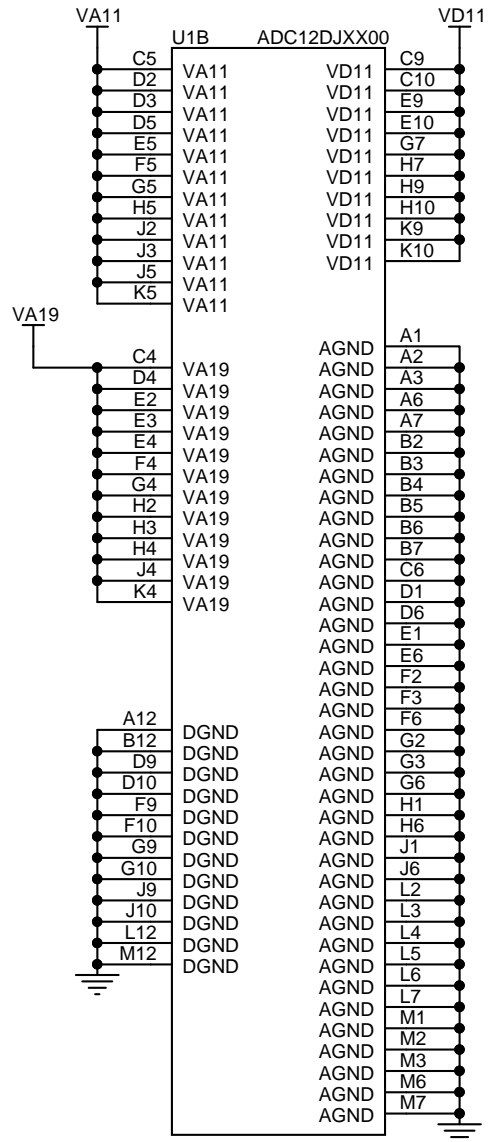


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Title: **ADC**

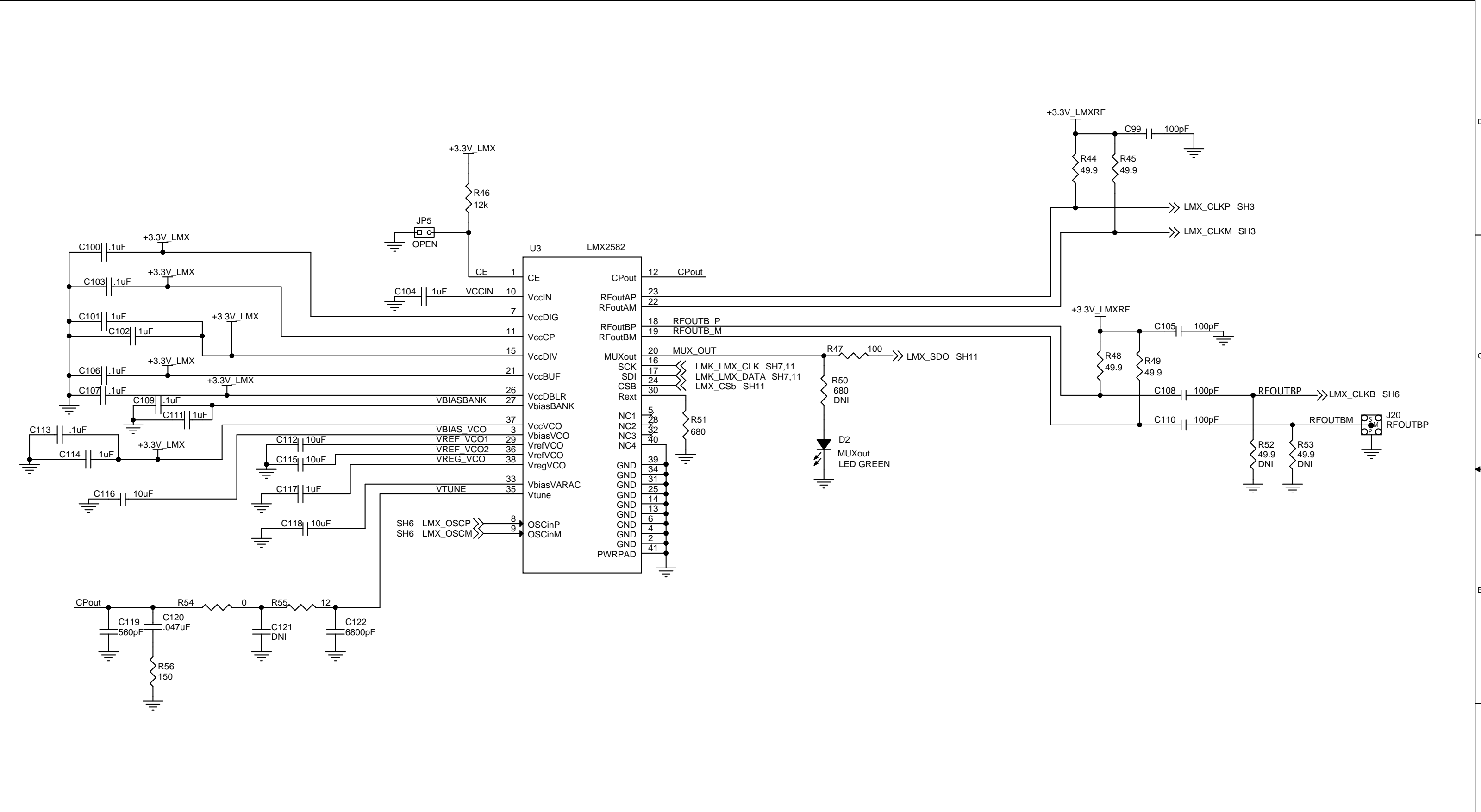
Size **B** Document Number: **TIDA-01442** Rev **A**

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Title		
ADC POWER		
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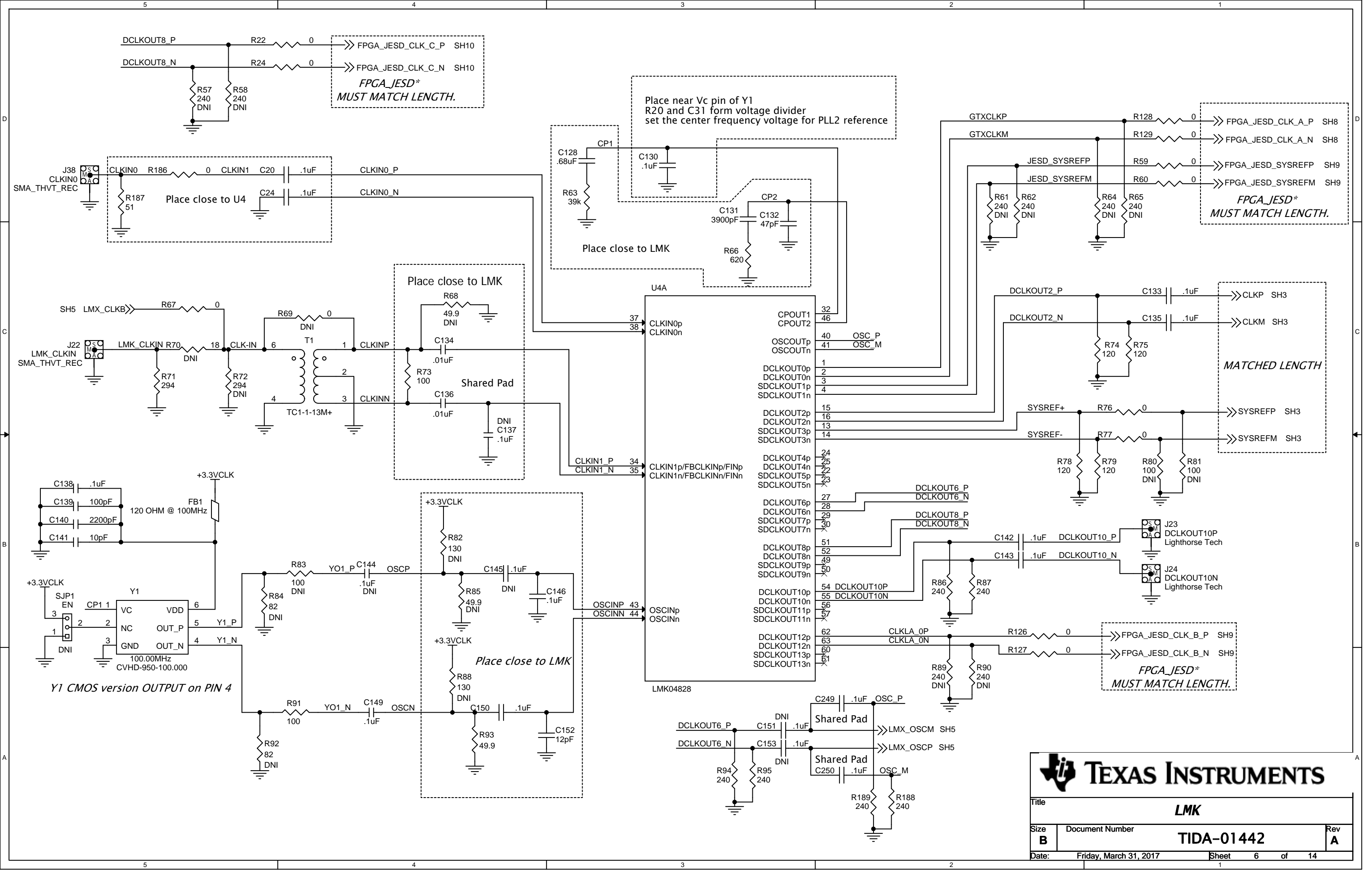


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LMX

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FPGA_JESD*
MUST MATCH LENGTH.

Place near Vc pin of Y1
R20 and C31 form voltage divider
set the center frequency voltage for PLL2 reference

Place close to U4

Place close to LMK

Place close to LMK

Shared Pad

Place close to LMK

FPGA_JESD*
MUST MATCH LENGTH.

MATCHED LENGTH

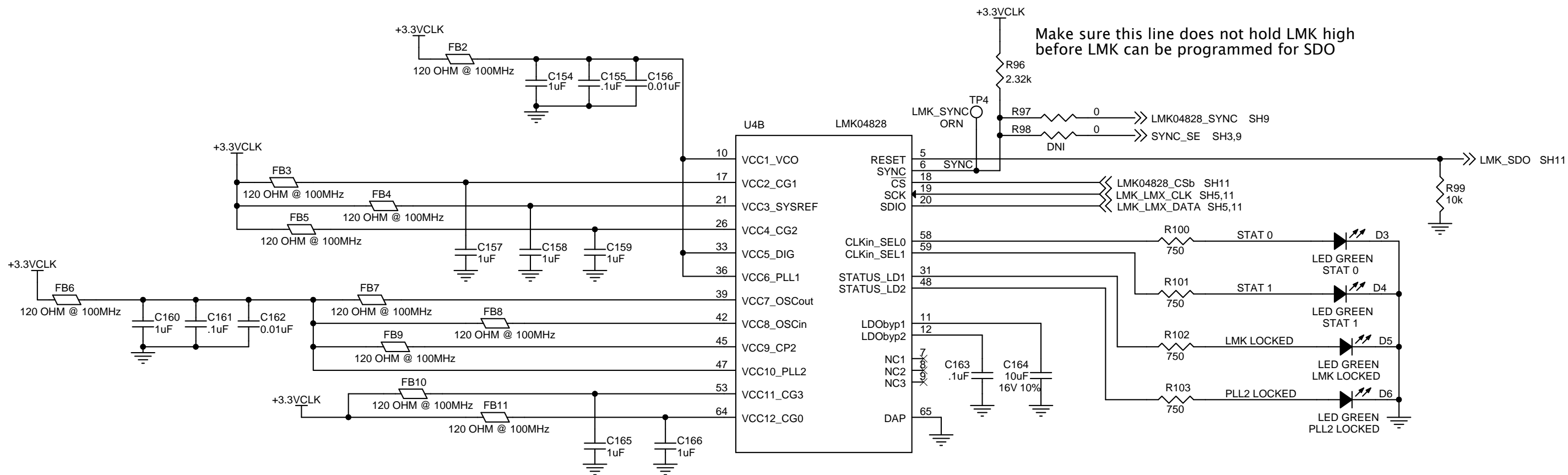
FPGA_JESD*
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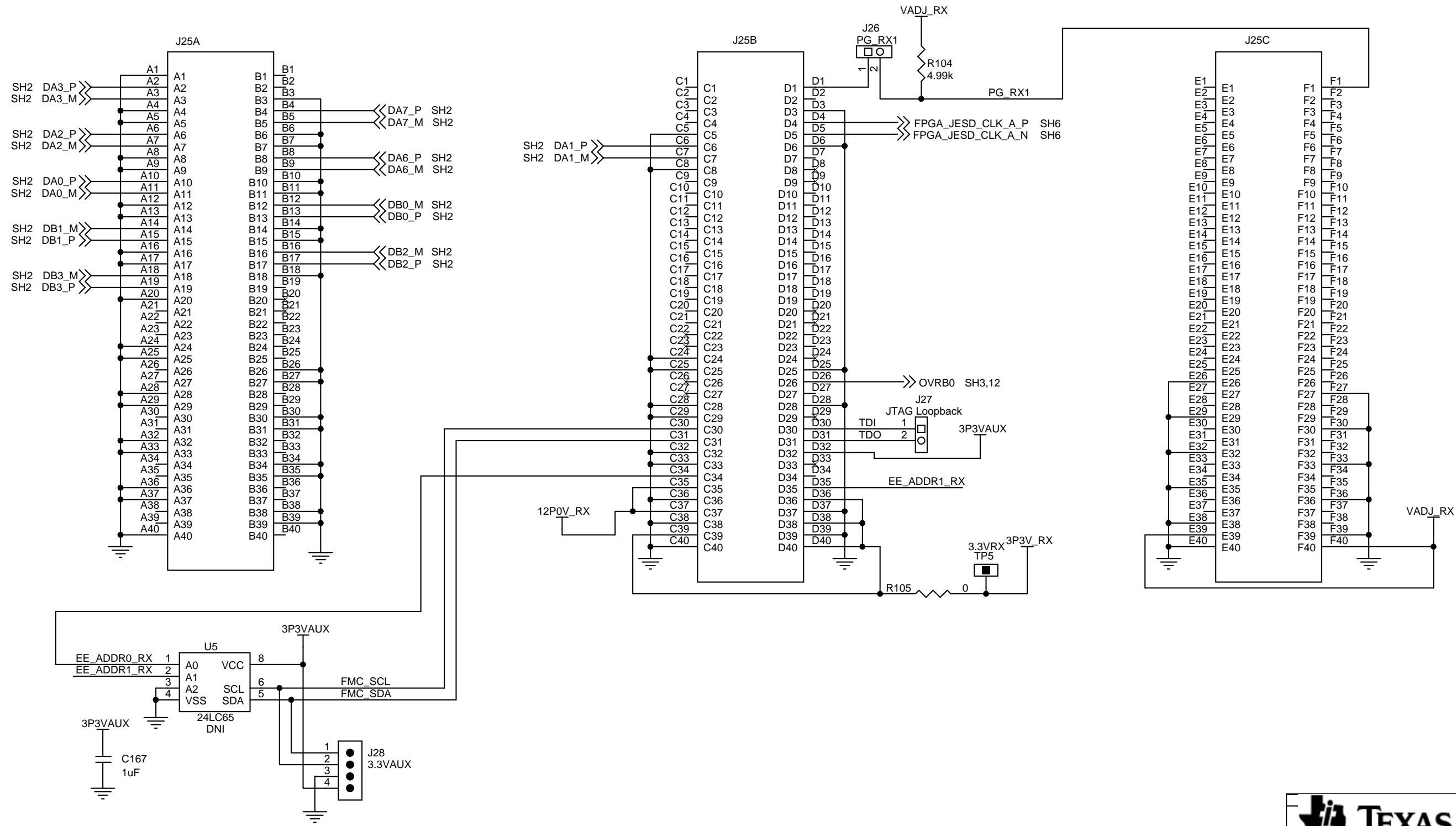
TEXAS INSTRUMENTS

Title: **LMK**

Size: **B** Document Number: **TIDA-01442** Rev: **A**

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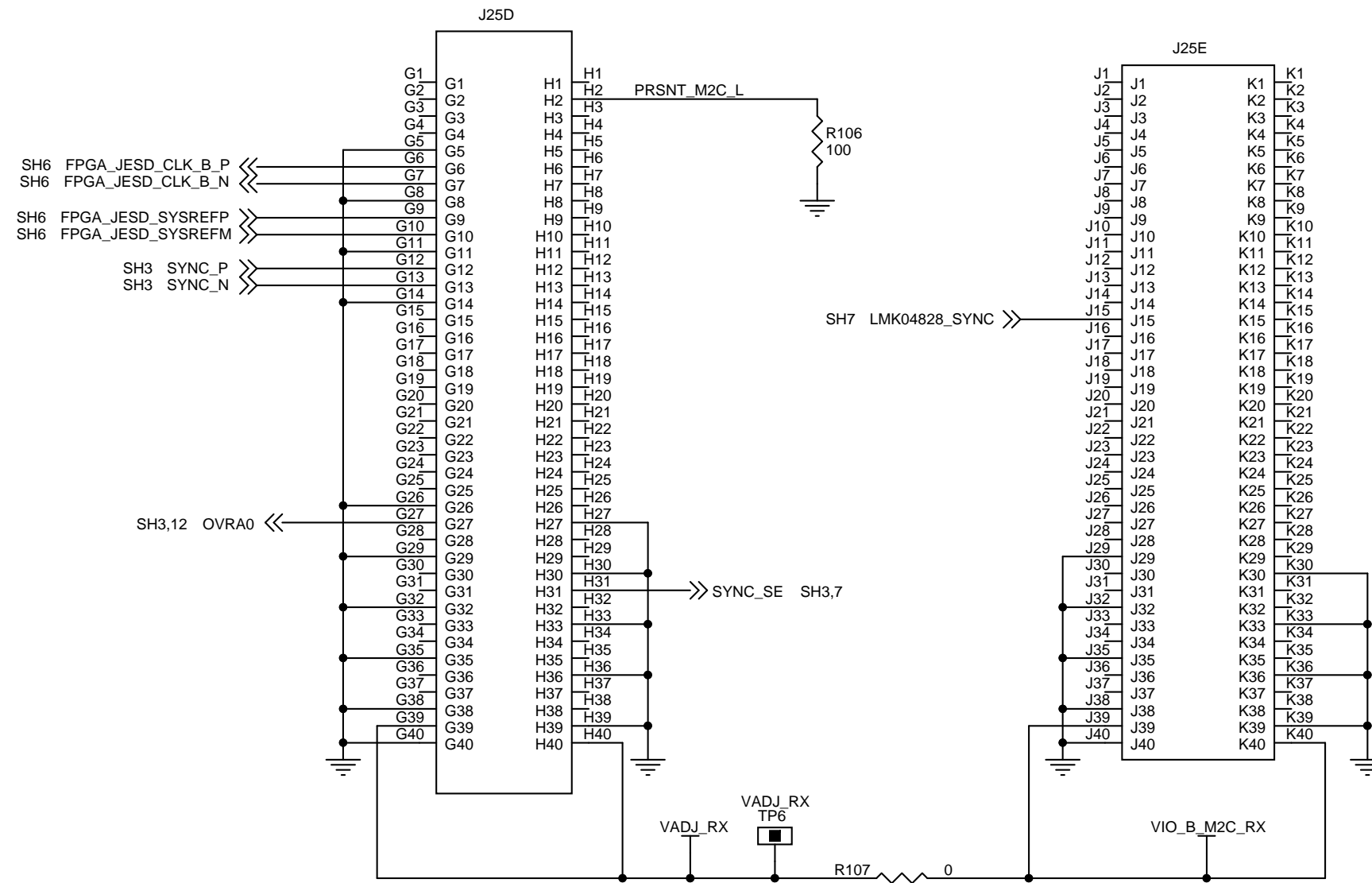




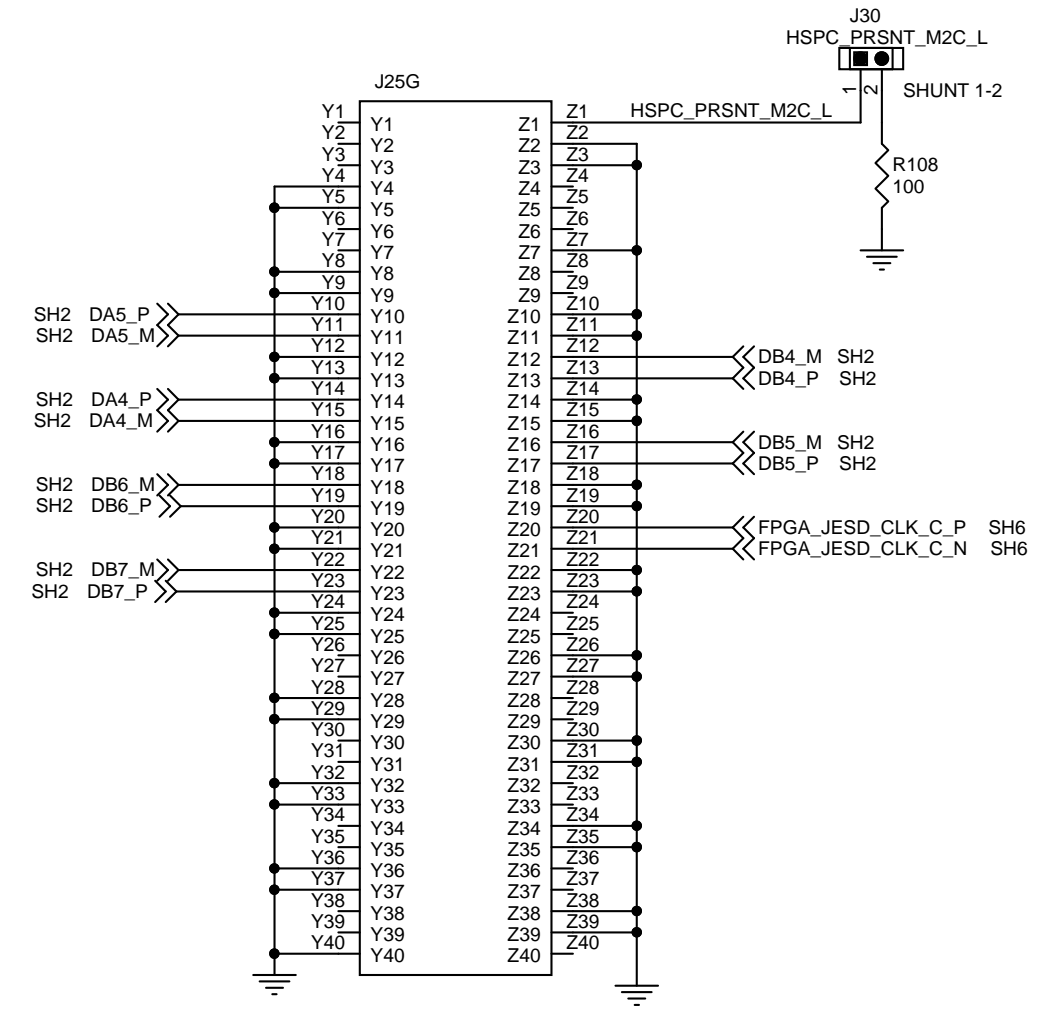
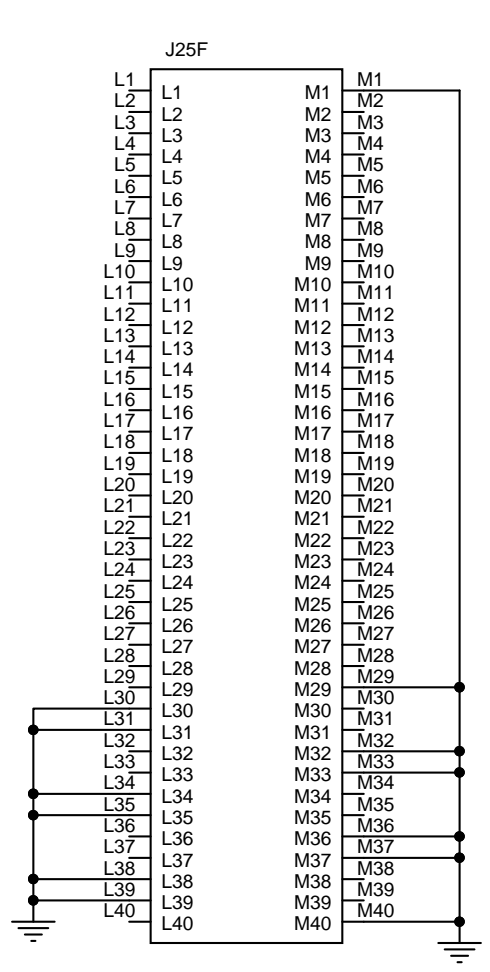
TEXAS INSTRUMENTS

Title: **OUTPUT - FMC CONNECTOR**

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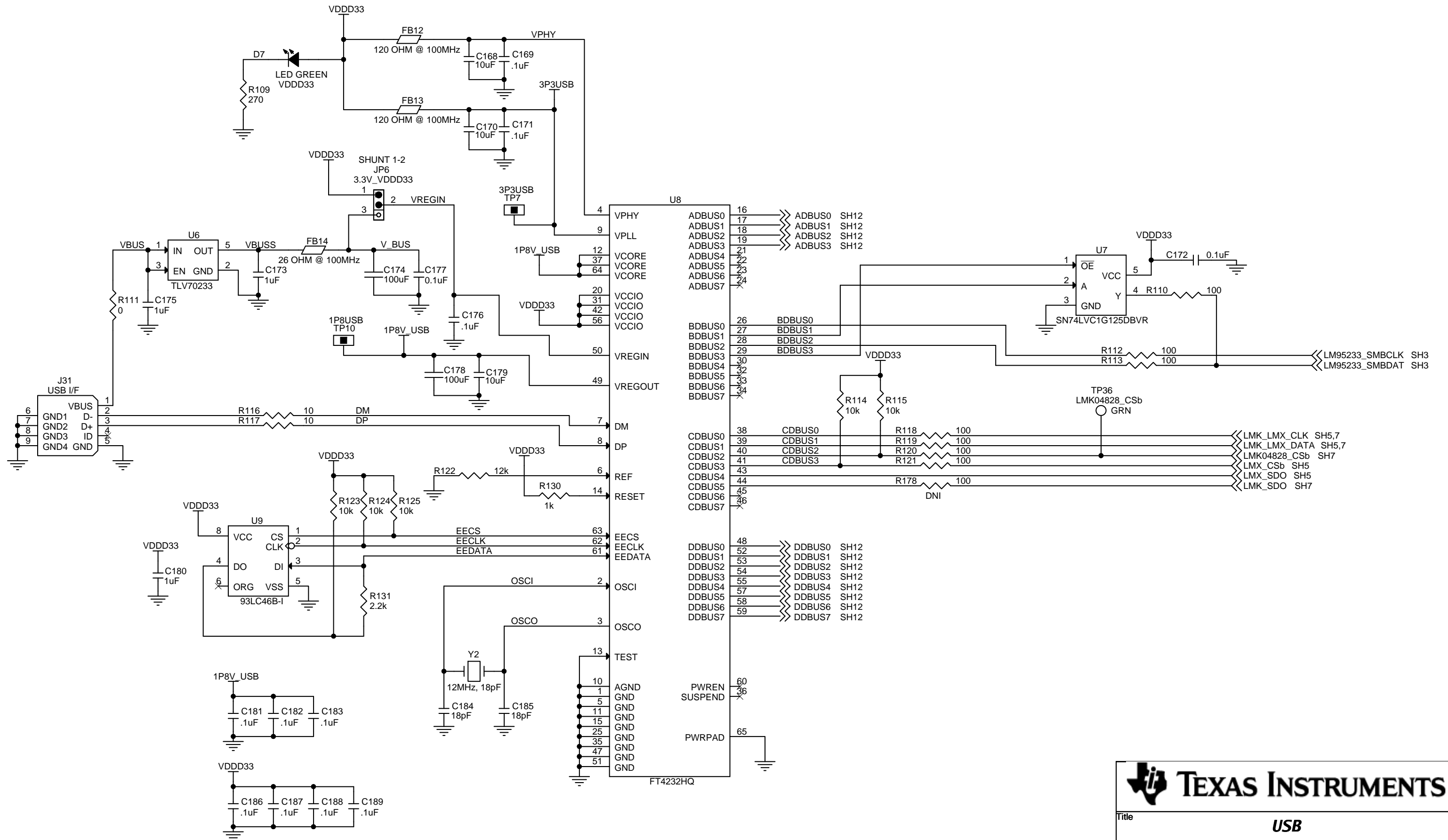
Title		
OUTPUT - FMC CONNECTOR		
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Title: **OUTPUT - FMC CONNECTOR**

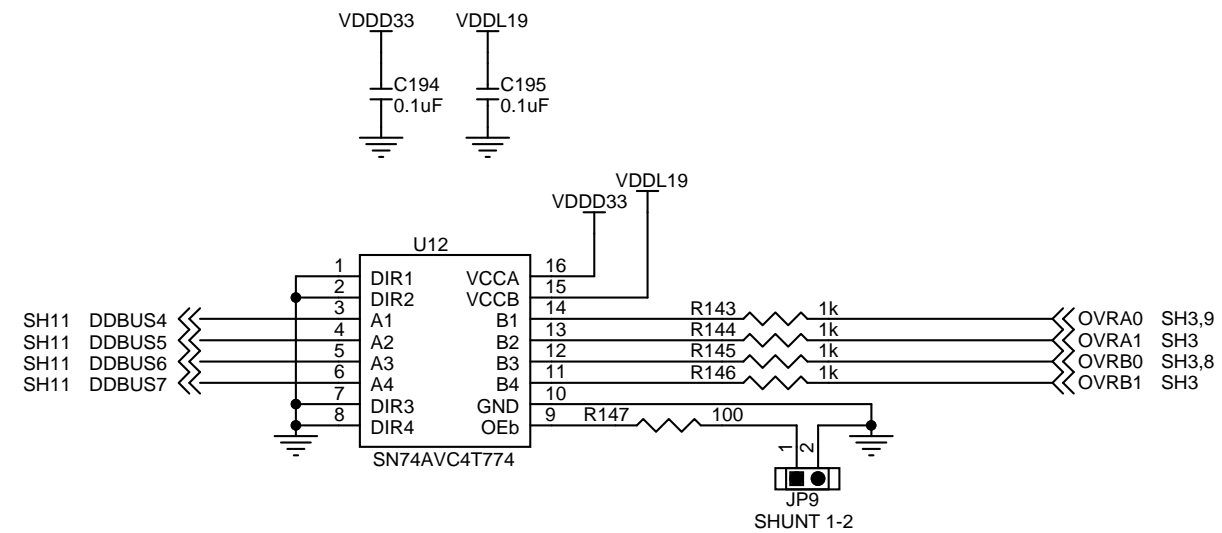
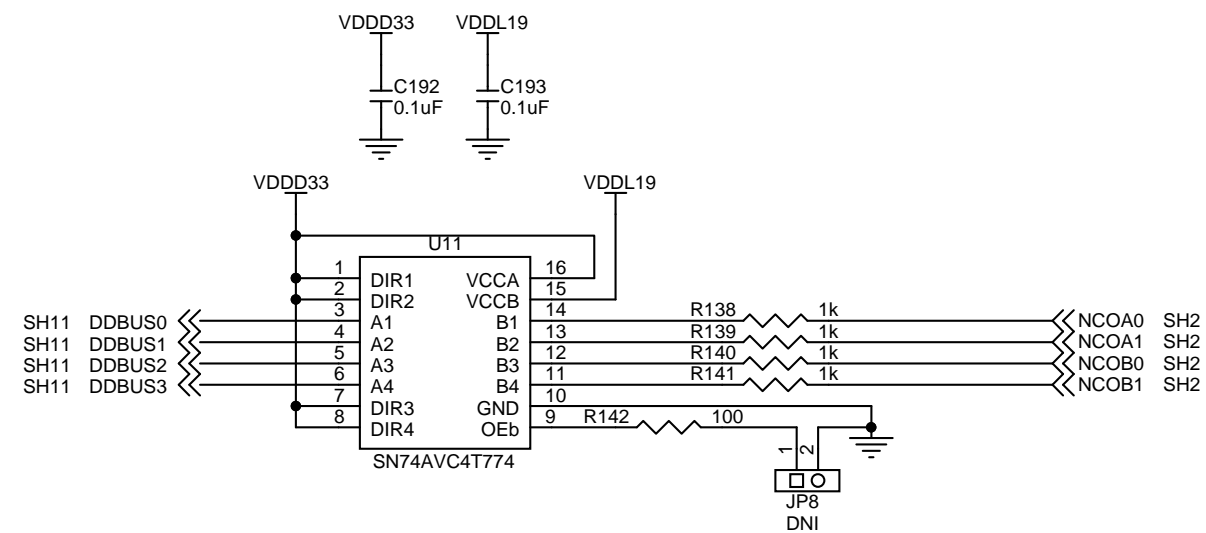
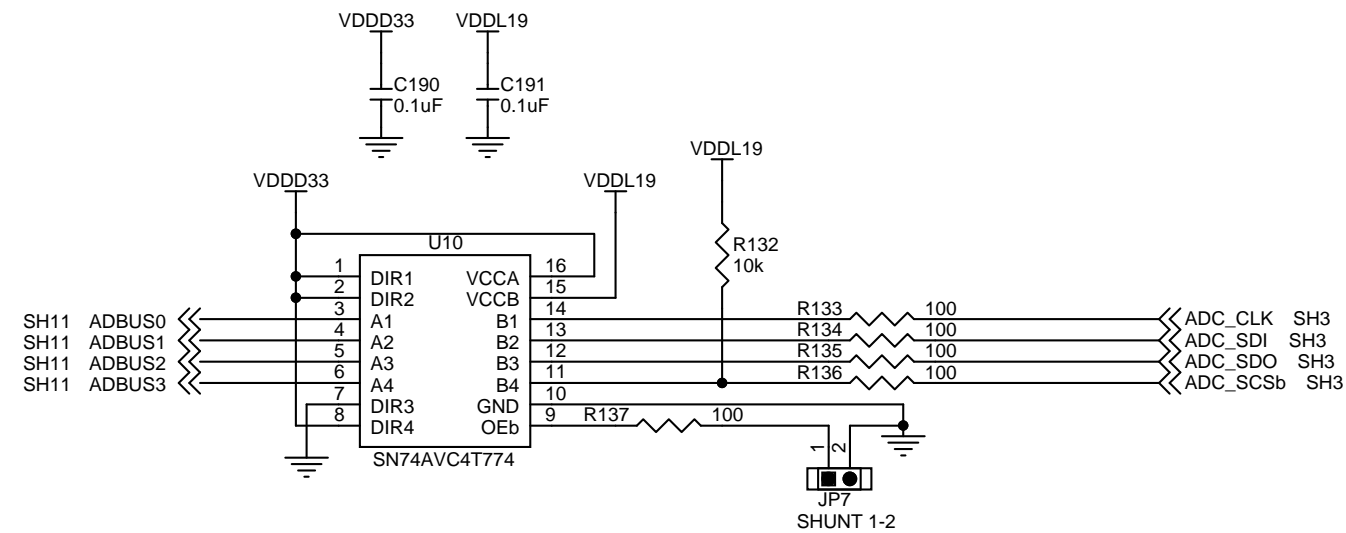
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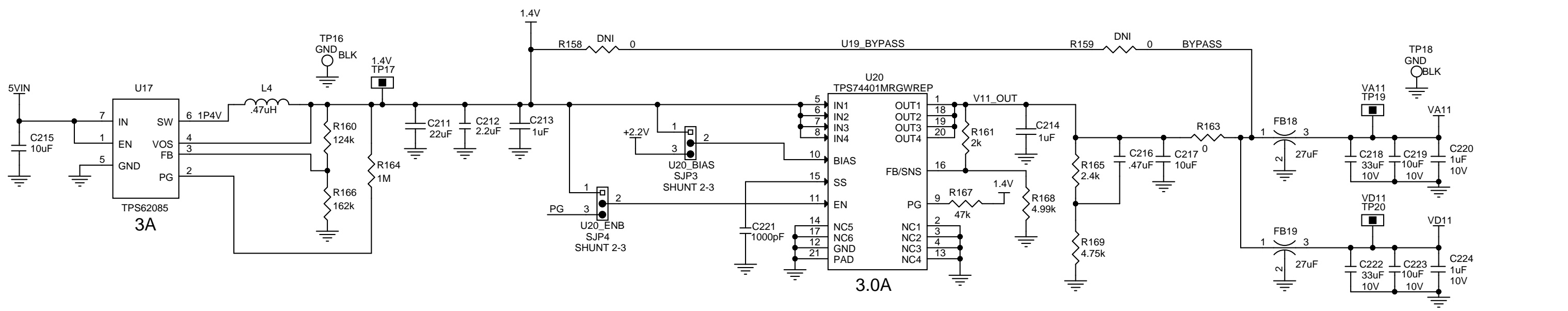
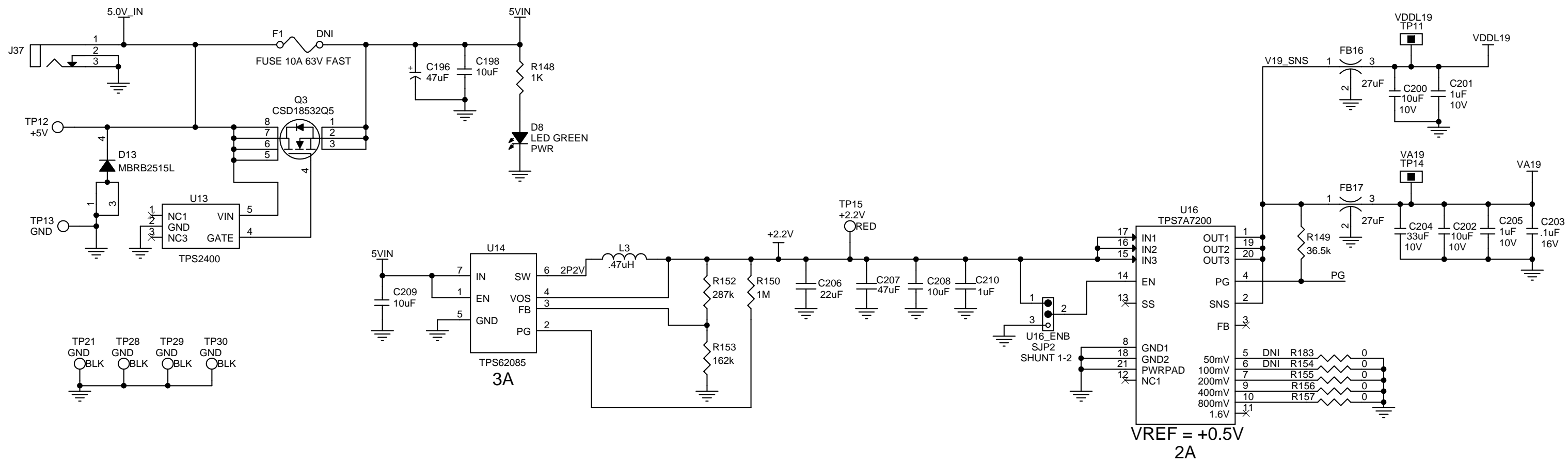
TEXAS INSTRUMENTS

Title: **USB**

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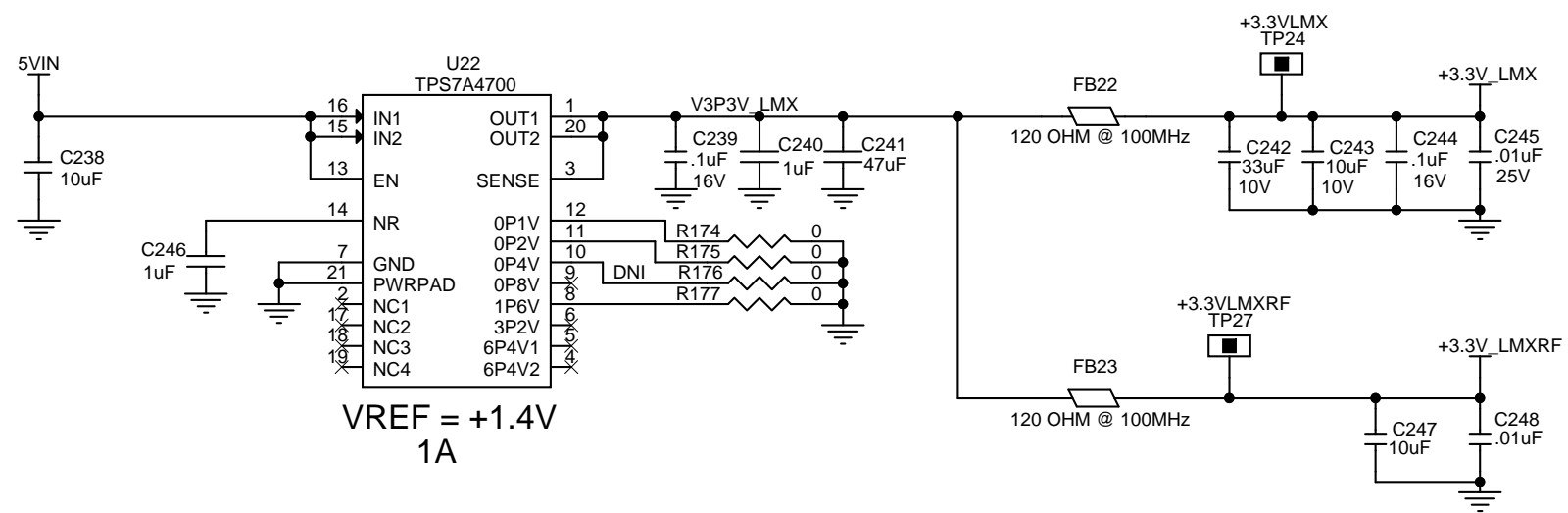
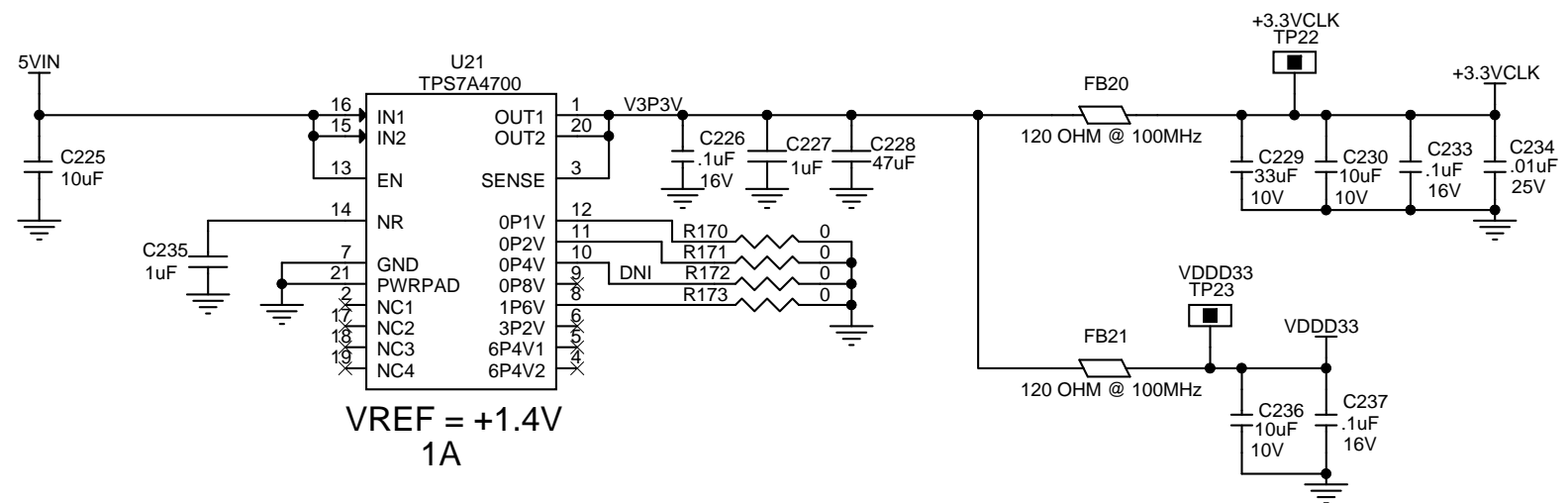
Title		
LEVEL SHIFTERS		
Size	Document Number	Rev
B	TIDA-01442	A
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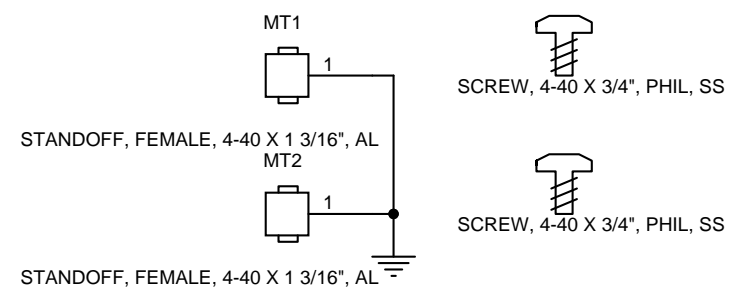
Title: **ADC POWER SUPPLIES**

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MECHANICAL PARTS

PCB
BARE BOARD, ADCXXDJXX00 HSP001



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